

OBSOLETE October 13, 2011

OUTPUT

GND

TIMING

TIMING

RESISTOR

697502

5

CAPACITOR

# **Tone Decoder**

### **General Description**

The LM567 and LM567C are general purpose tone decoders designed to provide a saturated transistor switch to ground when an input signal is present within the passband. The circuit consists of an I and Q detector driven by a voltage controlled oscillator which determines the center frequency of the decoder. External components are used to independently set center frequency, bandwidth and output delay.

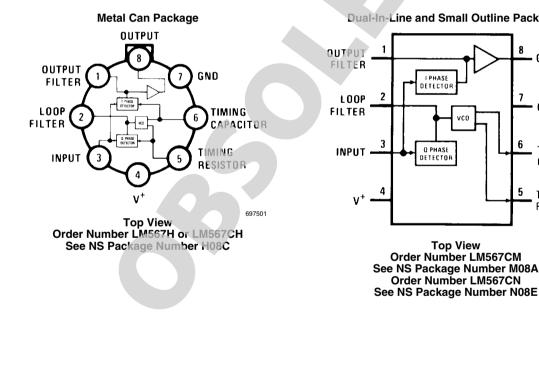
### Features

- 20 to 1 frequency range with an external resistor
- Logic compatible output with 100 mA current sinking capability
- Bandwidth adjustable from 0 to 14%

- High rejection of out of band signals and noise
- Immunity to false signals
- Highly stable center frequency
- Center frequency adjustable from 0.01 Hz to 500 kHz

## **Applications**

- Touch tone decoding
- Precision oscillator
- Frequency monitoring and control
- Wide band FSK demodulation
- Ultrasonic controls -
- Carrier current remote controls
- Communications paging decoders



## **Connection Diagrams**

© 2011 National Semiconductor Corporation 6975 Dual-In-Line and Small Outline Packages

### Absolute Maximum Ratings (Note 1)

If Military/Aerospace specified devices are required, please contact the National Semiconductor Sales Office/ Distributors for availability and specifications.

Supply Voltage Pin	9V
Power Dissipation (Note 2)	1100 mW
V <sub>8</sub>	15V
V <sub>3</sub>	-10V
V <sub>3</sub>	$V_4 + 0.5V$
Storage Temperature Range	–65°C to +150°C
Operating Temperature Range	

LM567H LM567CH, LM567CM, LM567CN	–55°C to +125°C 0°C to +70°C			
Soldering Information				
Dual-In-Line Package				
Soldering (10 sec.)	260°C			
Small Outline Package				
Vapor Phase (60 sec.)	215°C			
Infrared (15 sec.)	220°C			
See AN-450 "Surface Mounting Methods and Their Effect				

on Product Reliability" for other methods of soldering surface mount devices.

## **Electrical Characteristics**

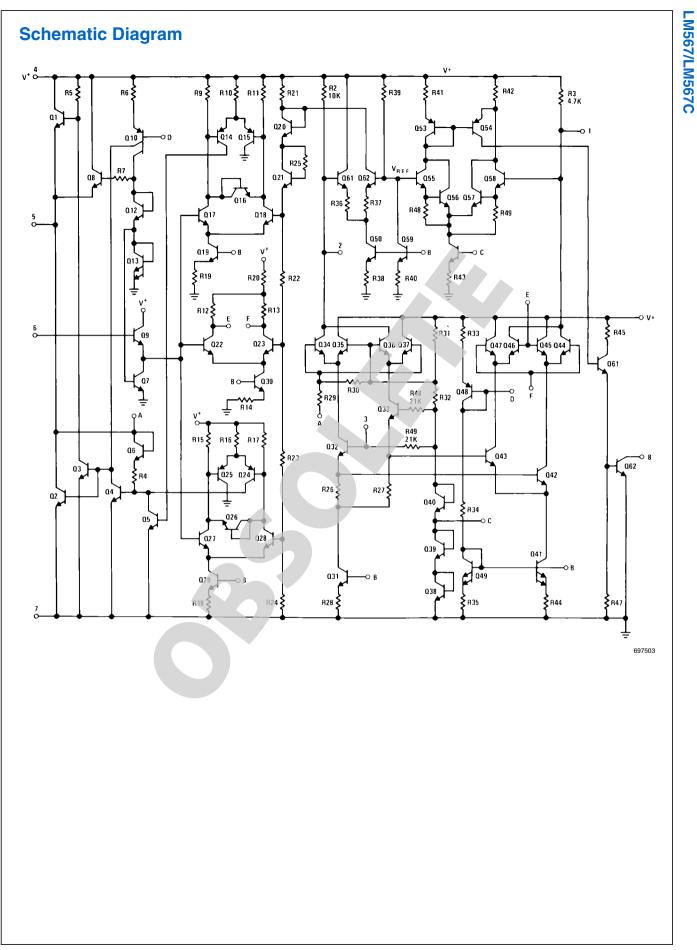
AC Test Circuit,  $T_{A} = 25^{\circ}C$ ,  $V^{+} = 5V$ 

Developmentering	Canditiana		LM567		LM567C/LM567CM			
Parameters	Conditions	Min Typ		Max	Min	Тур	Max	Units
Power Supply Voltage Range		4.75	5.0	9.0	4.75	5.0	9.0	V
Power Supply Current Quiescent	$R_L = 20k$		6	8		7	10	mA
Power Supply Current Activated	$R_L = 20k$		11	13		12	15	mA
Input Resistance		18	20		15	20		kΩ
Smallest Detectable Input Voltage	$I_{L} = 100 \text{ mA}, f_{i} = f_{o}$		20	25		20	25	mVrms
Largest No Output Input Voltage	$I_{\rm C} = 100 \text{ mA}, f_{\rm i} = f_{\rm o}$	10	15		10	15		mVrms
Largest Simultaneous Outband Signal to Inband Signal Ratio			6			6		dB
Minimum Input Signal to Wideband Noise Ratio	B <sub>n</sub> = 140 kHz		-6			-6		dB
Largest Detection Bandwidth		12	14	16	10	14	18	% of f <sub>o</sub>
Largest Detection Bandwidth Skew			1	2		2	3	% of f <sub>o</sub>
Largest Detection Bandwidth Variation with Temperature			±0.1			±0.1		%/°C
Largest Detection Bandwidth Variation with Supply Voltage	<b>4.75</b> –6.75V		±1	±2		±1	±5	%V
Highest Center Frequency		100	500		100	500		kHz
Center Frequency Stability (4.75–5.75V)	0 < T <sub>A</sub> < 70 -55 < T <sub>A</sub> < +125		35 ± 60 35 ± 140			35 ± 60 35 ± 140		ppm/°C ppm/°C
Center Frequency Shift with Supply Voltage	4.75V-6.75V 4.75V-9V		0.5	1.0 2.0		0.4	2.0 2.0	%/V %/V
Fastest ON-OFF Cycling Rate			f <sub>o</sub> /20			f <sub>o</sub> /20		
Output Leakage Current	V <sub>8</sub> = 15V		0.01	25		0.01	25	μA
Output Saturation Voltage	e <sub>i</sub> = 25 mV, I <sub>8</sub> = 30 mA e <sub>i</sub> = 25 mV, I <sub>8</sub> = 100 mA		0.2 0.6	0.4 1.0		0.2 0.6	0.4 1.0	V
Output Fall Time	-	1	30			30		ns
Output Rise Time			150			150		ns

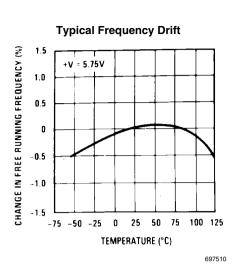
Note 1: Absolute Maximum Ratings indicate limits beyond which damage to the device may occur. Operating Ratings indicate conditions for which the device is functional, but do not guarantee specific performance limits. Electrical Characteristics state DC and AC electrical specifications under particular test conditions which guarantee specific performance limits. This assumes that the device is within the Operating Ratings. Specifications are not guaranteed for parameters where no limit is given, however, the typical value is a good indication of device performance.

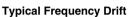
Note 2: The maximum junction temperature of the LM567 and LM567C is 150°C. For operating at elevated temperatures, devices in the TO-5 package must be derated based on a thermal resistance of 150°C/W, junction to ambient or 45°C/W, junction to case. For the DIP the device must be derated based on a thermal resistance of 110°C/W, junction to ambient. For the Small Outline package, the device must be derated based on a thermal resistance of 160°C/W, junction to ambient.

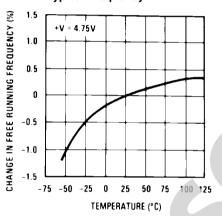
Note 3: Refer to RETS567X drawing for specifications of military LM567H version.

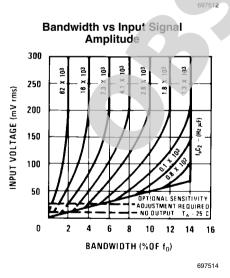


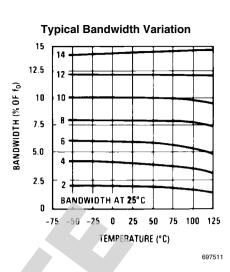
# **Typical Performance Characteristics**



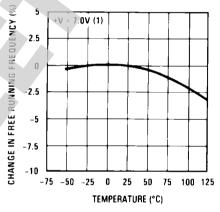






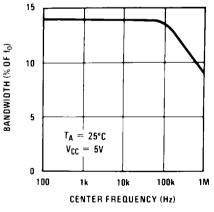


**Typical Frequency Drift** 

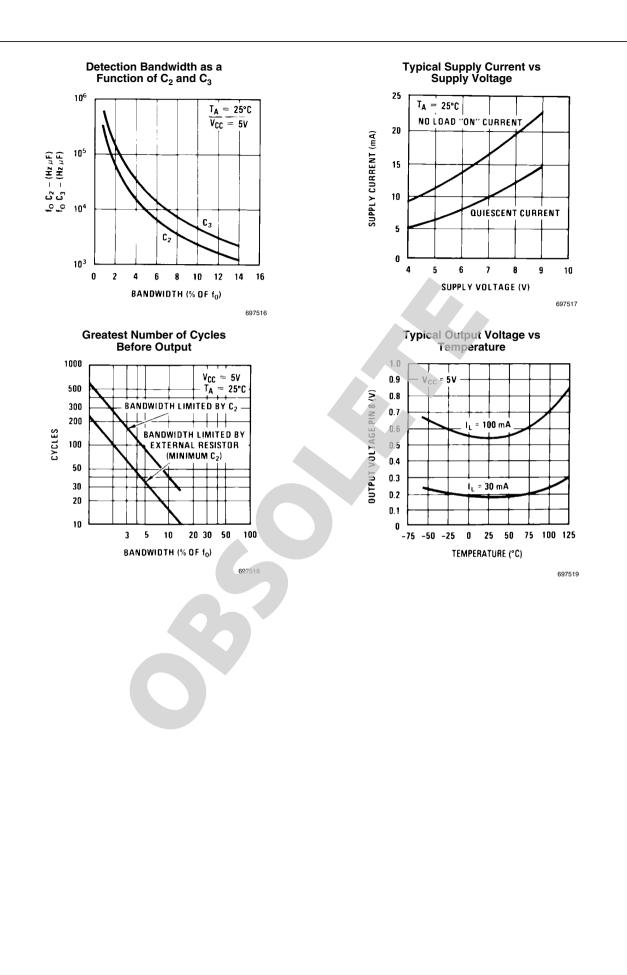


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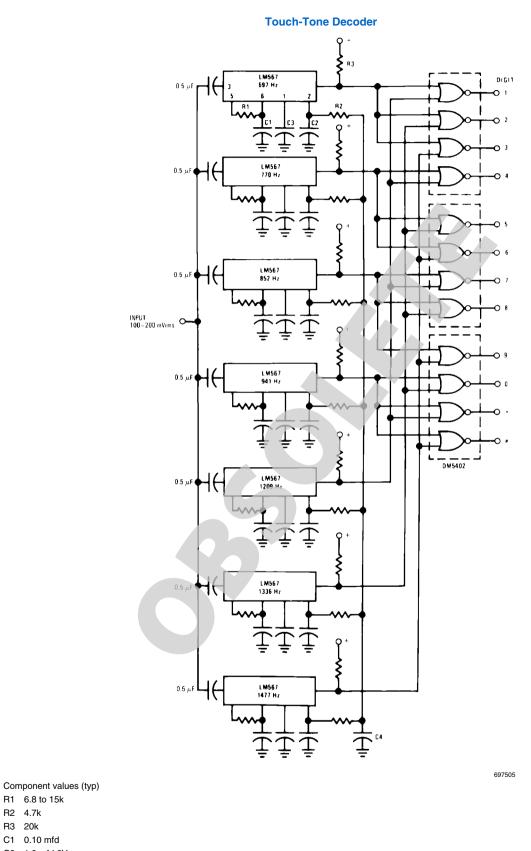
#### Largest Detection Bandwidth



697515



# **Typical Applications**



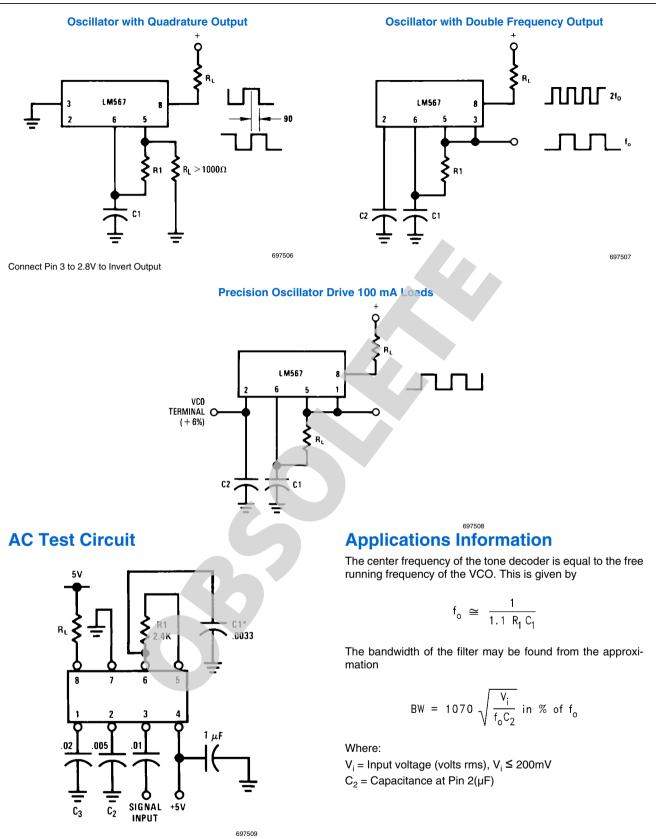
LM567/LM567C

C3

R1 6.8 to 15k R2 4.7k R3 20k C1 0.10 mfd C2

1.0 mfd 6V

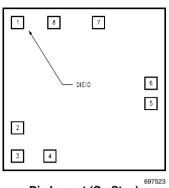
2.2 mfd 6V C4 250 mfd 6V



$$\label{eq:fi} \begin{split} f_i &= 100 \text{ kHz} + 5\text{V} \\ \text{*Note: Adjust for } f_o &= 100 \text{ kHz}. \end{split}$$

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# LM567C MDC MWC Tone Decoder



Die Layout (C - Step)

# **Die/Wafer Characteristics**

Fabrication Attribu	tes	General Die Information			
Physical Die Identification	LM567C	Bond Pad Opening Size (min)	91µm x 91µm		
Die Step	С	Bond Pad Metalization	0.5% COPPER_BAL. ALUMINUM		
Physical Attribute	Physical Attributes		VOM NITRIDE		
Wafer Diameter	150mm	Back Side Metal	BARE BACK		
Dise Size (Drawn)	1600µm x 1626µm 63.0mils x 64.0mils	Back Side Connection	Floating		
Thickness	406µm Nominal				
Min Pitch	198µm Nominal				

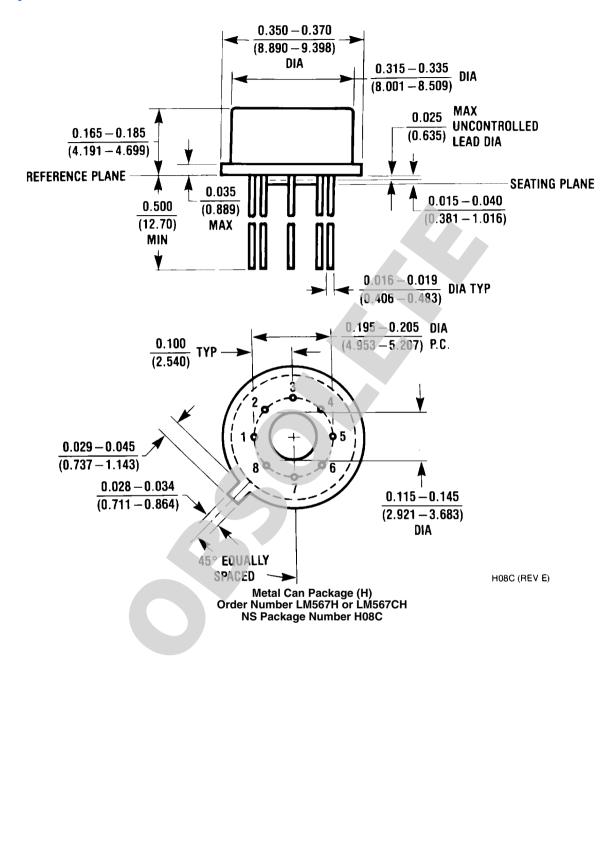
### Special Assembly Requirements:

Note: Actual die size is rounded to the nearest micron.

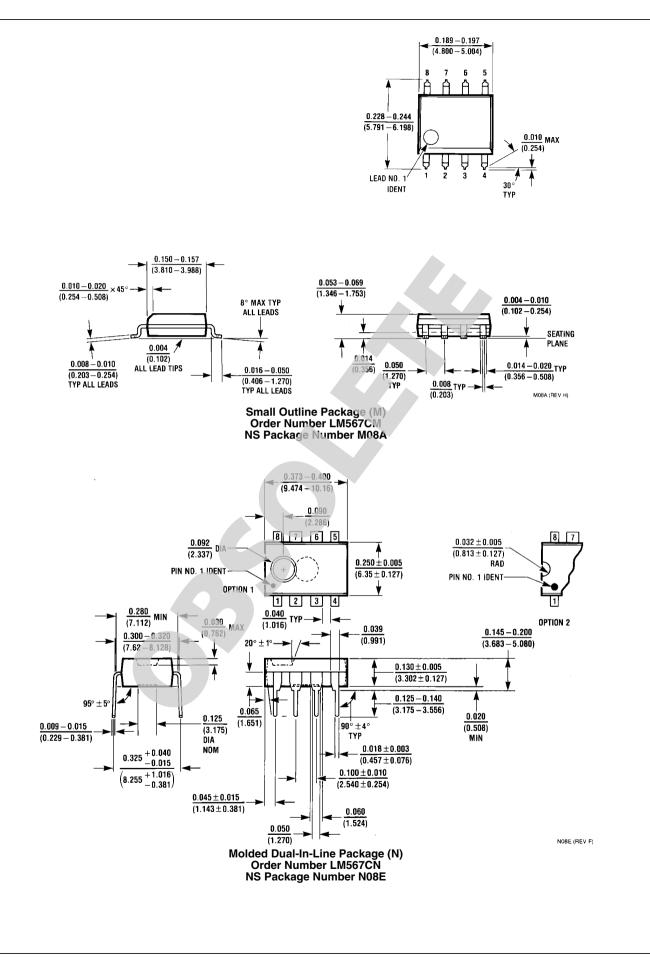
Die Bond Pad Coordinate Locations (C - Step)							
(Referenced to die center, coordinates in µm) NC = No Connection, N.U. = Not Used							
SIGNAL NAME		X/Y COORDINATES		PAD SIZE			
	PAD# NUMBER	X	Y	X		Y	
OUTPUT FILTER	1	-673	686	91	x	91	
LOOP FILTER	2	-673	-419	91	x	91	
INPUT	3	-673	-686	91	x	91	
V+	4	-356	-686	91	x	91	
TIMING RES	5	673	-122	91	x	91	
TIMING CAP	6	673	76	91	x	91	
GND	7	178	686	117	x	91	
OUTPUT	8	-318	679	117	x	104	

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Tel:	(852) 27371701
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Tel:	81 043 299 2308

### Physical Dimensions inches (millimeters) unless otherwise noted



LM567/LM567C



# Notes

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